

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent Cdv/dt effect decline
- ★ Advanced high cell density Trench technology

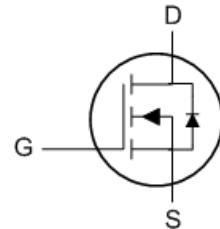
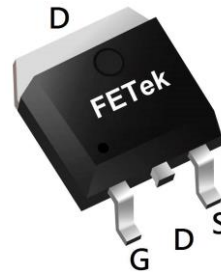
**Product Summary**


BVDSS	RDSON	ID
100V	22mΩ	40A

**Description**

The FKH0026 is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The FKH0026 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

**TO263 Pin Configuration**

**Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	100	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	40	A
I <sub>D</sub> @T <sub>C</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	22	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	75	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	16	mJ
I <sub>AS</sub>	Avalanche Current	18	A
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	62.5	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	---	50	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	2	°C/W

**Electrical Characteristics ( $T_J=25\text{ }^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	100	---	---	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10V, I_D=9A$	---	16	22	m $\Omega$
		$V_{GS}=4.5V, I_D=7A$	---	20	28	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	---	2.5	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=80V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	$\mu A$
		$V_{DS}=80V, V_{GS}=0V, T_J=55^\circ\text{C}$	---	---	100	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA
$g_{fs}$	Forward Transconductance	$V_{DS}=5V, I_D=9A$	---	28	---	S
$R_g$	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$	---	1.6	---	$\Omega$
$Q_g$	Total Gate Charge (10V)	$V_{DS}=80V, V_{GS}=10V, I_D=7A$	---	36	---	nC
$Q_{gs}$	Gate-Source Charge		---	5	---	
$Q_{gd}$	Gate-Drain Charge		---	10	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=50V, V_{GS}=10V, R_G=3.3\Omega$ $I_D=7A$	---	11.5	---	ns
$T_r$	Rise Time		---	29	---	
$T_{d(off)}$	Turn-Off Delay Time		---	42	---	
$T_f$	Fall Time		---	18	---	
$C_{iss}$	Input Capacitance	$V_{DS}=15V, V_{GS}=0V, f=1\text{MHz}$	---	1930	---	pF
$C_{oss}$	Output Capacitance		---	245	---	
$C_{rss}$	Reverse Transfer Capacitance		---	125	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current <sup>1,6</sup>	$V_G=V_D=0V, \text{Force Current}$	---	---	40	A
$I_{SM}$	Pulsed Source Current <sup>2,6</sup>		---	---	75	A
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$	---	---	1.2	V
$t_{rr}$	Reverse Recovery Time	$I_F=7A, di/dt=100A/\mu s,$	---	48	---	nS
$Q_{rr}$	Reverse Recovery Charge	$T_J=25^\circ\text{C}$	---	29	---	nC

## Note :

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$
3. The EAS data shows Max. rating. The test condition is  $V_{DD}=25V, V_{GS}=10V, L=0.1\text{mH}$
4. The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
5. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.

Typical Characteristics

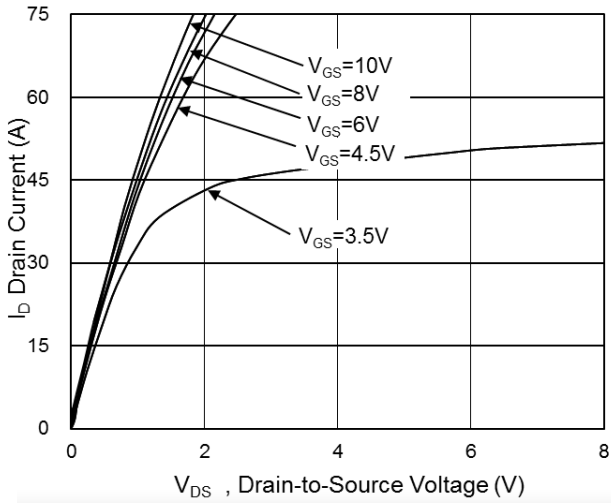


Fig.1 Typical Output Characteristics

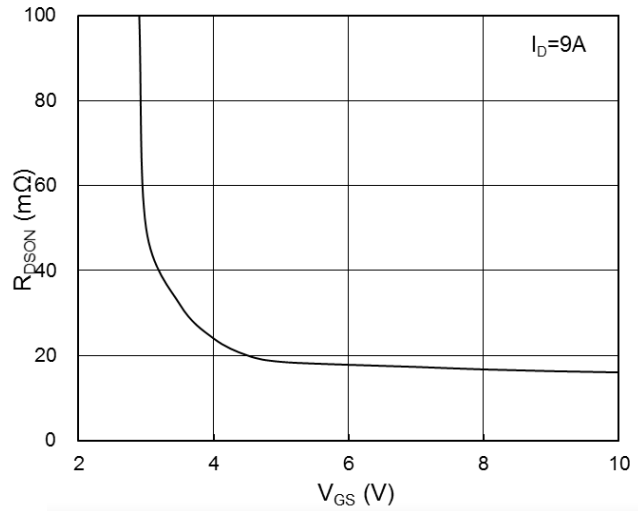


Fig.2 On-Resistance vs. Gate-Source Voltage

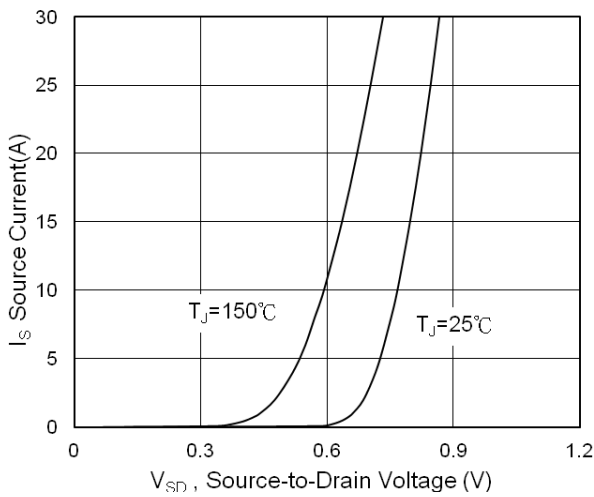


Fig.3 Forward Characteristics of Reverse

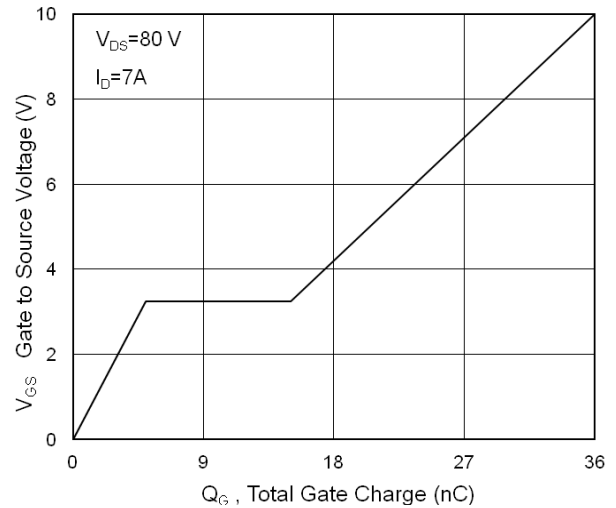


Fig.4 Gate-Charge Characteristics

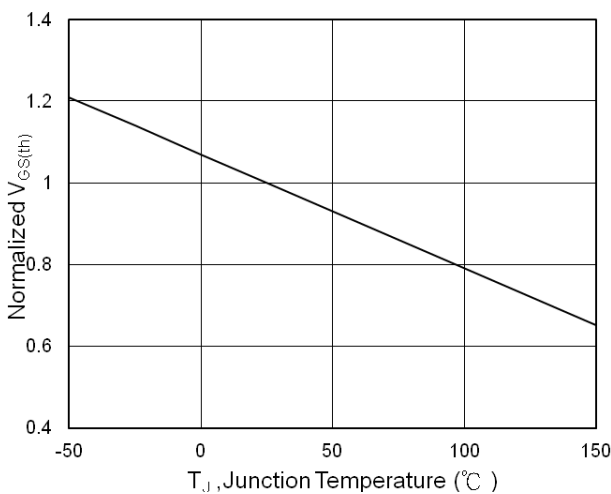


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

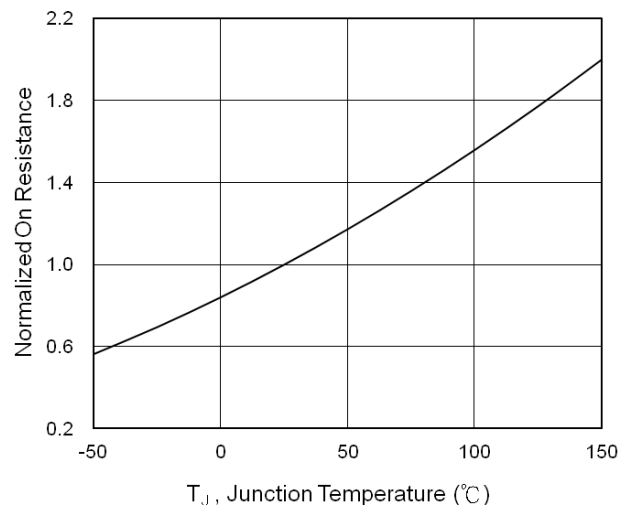


Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$

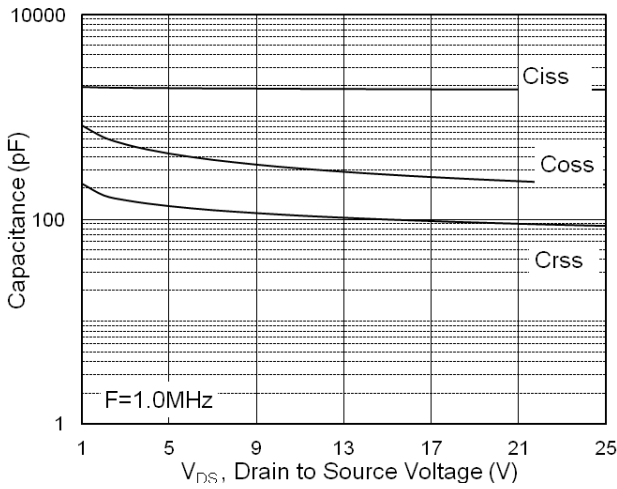


Fig.7 Capacitance

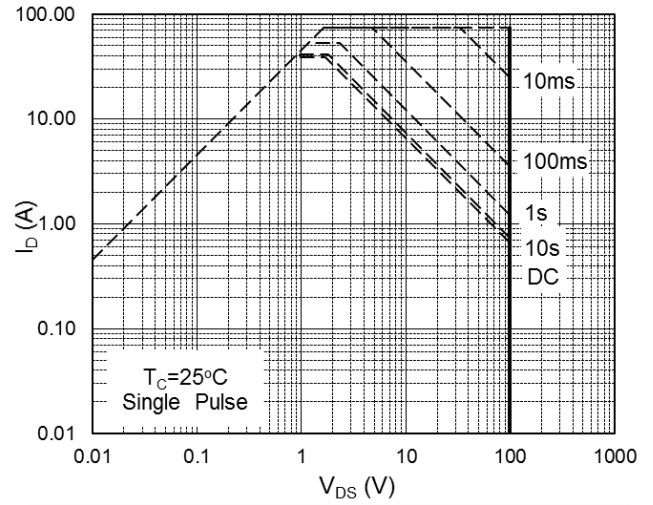


Fig.8 Safe Operating Area

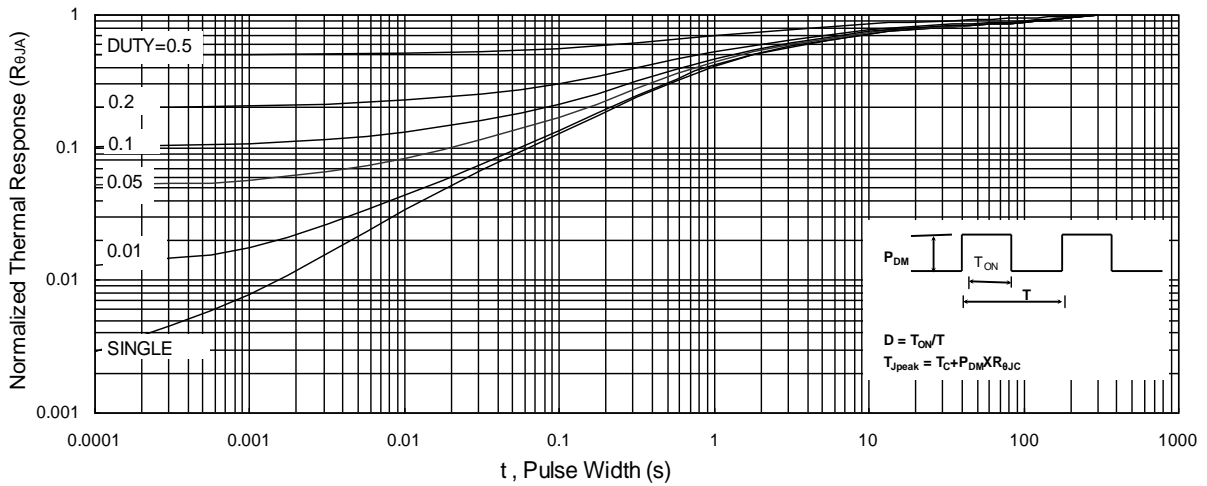


Fig.9 Normalized Maximum Transient Thermal Impedance

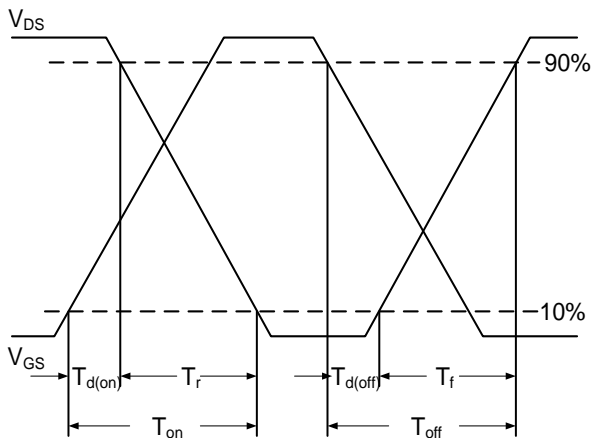


Fig.10 Switching Time Waveform

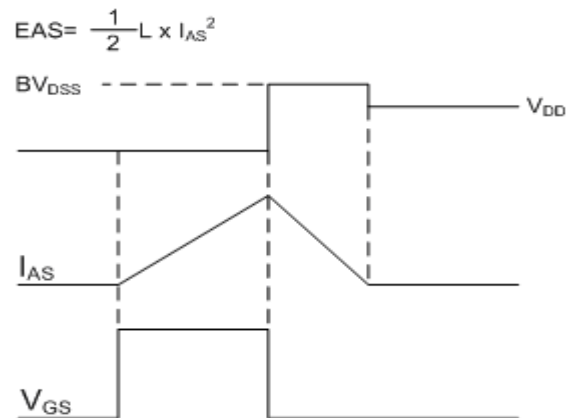
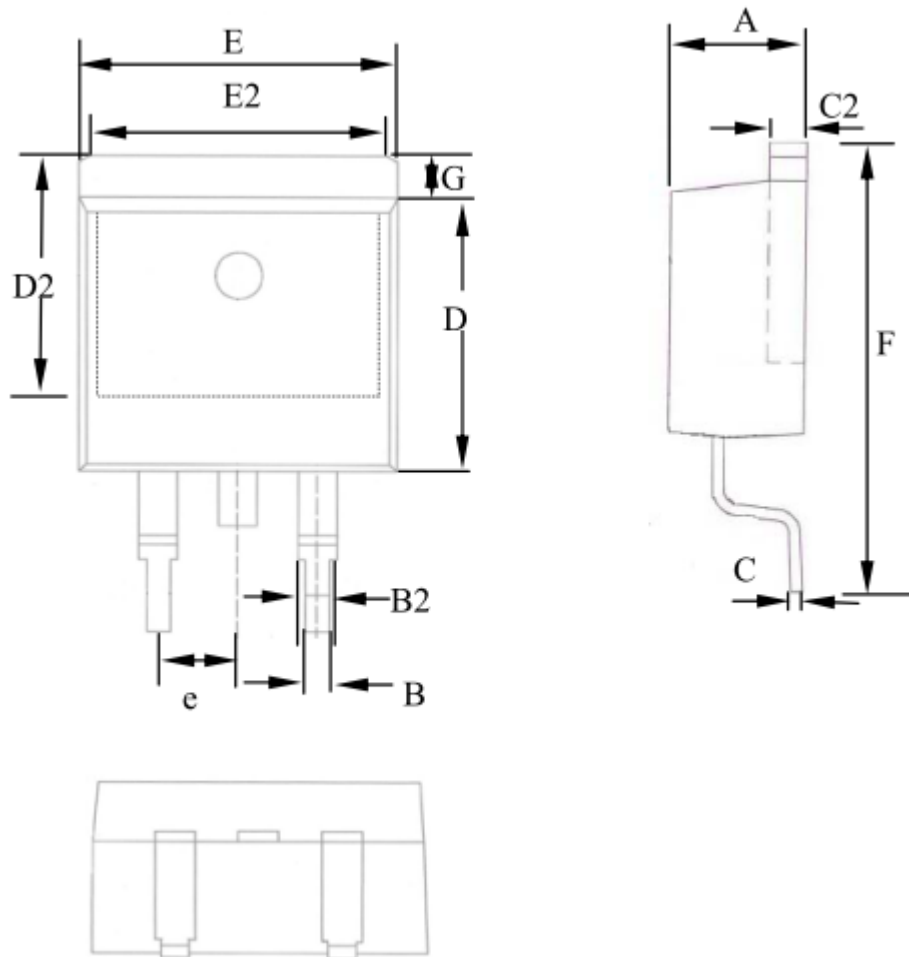


Fig.11 Unclamped Inductive Switching Waveform

## TO263 Package Outline Dimensions



SYMBOLS	MILLIMETERS			INCHES		
	MIN	NOM		MIN	NOM	
A	4.40	4.57	4.70	0.173	0.180	0.185
B	0.77	—	0.90	0.030	—	0.035
B2	1.23	—	1.36	0.048	—	0.054
C	0.34	—	0.47	0.013	—	0.019
C2	1.22	—	1.32	0.048	—	0.052
D	8.60	8.70	8.80	0.339	0.343	0.346
D2	7.20	7.40	7.60	0.283	0.291	0.299
E	10.06	10.16	10.26	0.396	0.400	0.404
E2	7.00	7.20	7.40	0.276	0.283	0.291
F	14.70	15.10	15.50	0.579	0.594	0.610
G	1.17	1.27	1.40	0.046	0.050	0.055
e	—	2.54	—	—	0.100	—